

# SL8X305 Microcontroller

# Legacy Device: Philips/Signetics S8X305

### **FEATURES**

- Fetch, Decode, and Execute a 16-bit Instruction in a minimum of 200ns (one machine cycle)
- Bit-oriented instruction set (addressable single- or multiple-bit subfields)
- Separate buses for instruction, instruction Address and 3– State I/O
- Thirteen 8-bit general-purpose working registers
- Source/destination architecture
- · Bipolar low-power Schottky technology/TTL inputs and outputs
- On-chip oscillator and timing generation
- Single +5V supply
- Multiple package options

#### PRODUCT DESCRIPTION

The Signetics 8X305 Microcontroller (Figure 1) is a high–speed bipolar microprocessor implemented with low–power Schottky technology. In a single chip, the 8X305 combines speed, flexibility, and a bit–oriented instruction set. These features and other basic characteristics of the chip combine to provide cost–effective solutions for a broad range of applications. The 8X305 is particularly useful in systems that require high–speed bit manipulations — sophisticated controllers, data communications, very fast interface control, and other applications of a similar nature.

The 8X305 can fetch, decode, and execute a 16-bit instruction word in a minimum of 200ns. Within one instruction cycle, the 8-bit data-processing path can be programmed to rotate, mask, shift, and/or merge single or multiple bit subfields and, in addition, perform an ALU operation; in the same instruction, an external data field can be input, processed, and output to a specified destination — likewise, single or multiple bit data fields can be internally moved from a given source to a given destination. To summarize, fixed or variable-length data fields can be fetched, processed, operated on by the ALU, and moved to a different location — all in a timeframe of 200ns. To interface with I/O and program memory, the 8X305 uses a 13-bit instruction bus, an 8-bit bidirectional multiplexed I/O data/address bus and a 5-bit I/O control bus.

A wide selection of I/O devices, interface chips, and specialpurpose parts are available for systems use. In most applications, the more powerful 8X305 is functionally interchangeable with its predecessor — the 8X300.



### ABSOLUTE MAXIMUM RATINGS

PARAMETER	DESCRIPTION	RATING	UNIT	
Vcc	Supply voltage	+7.0	v	
X1, X2	Crystal input voltage	2.0	v	
All other pins	Logic input pins VI	5.5	. V	
T <sub>STG</sub>	Storage temperature range	-65 to +150	°C	

# DC ELECTRICAL CHARACTERISTICS 4.5V $\leq$ V<sub>CC</sub> $\leq$ 5.5V, -55°C $\leq$ T<sub>C</sub> $\leq$ + 125°C unless otherwise noted.

SYMBOL		TEAT CONDITIONS	LIMITS				COMMENTS	
	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT	COMMENTS	
Vcc	Supply voltage		4.75	5.0	5.5	v		
VIH	High level input voltage		0.6 2.0		2.0	v	X1 and X2 All other pins	
VIL	Low level input voltage				0.4 0.8	v	X1 and X2 All other pins	
V <sub>OH</sub>	High level output voltage	V <sub>CC</sub> = MIN; I <sub>OH</sub> = -3mA	2.4			v		
VOL	Low level output voltage	$V_{CC} = MIN; I_{OL} = 6mA$ $V_{CC} = MIN; I_{OL} = 16mA$	~		0.55 0.55	v	A <sub>0</sub> through A <sub>12</sub> All other outputs	
VCR	Regulator voltage	V <sub>CC</sub> = 5V		3.5 3.1 2.6		v	$T_A = -55^{\circ}C$ $T_A = 0^{\circ}C$ $T_C = 125^{\circ}C$	
Vik	Input clamp voltage	V <sub>CC</sub> = MIN; I <sub>I</sub> = -10mA			-1.5	v	Crystal inputs X1 and X2 do not have internal clamp diodes.	
Чн	High level input current	$V_{CC} = MAX \qquad \begin{array}{c} V_{IH} = 0.6V \\ V_{IH} = 4.5V \end{array}$			4.0 50	mA μA	X1 and X2 All other pins	
կլ	Low-level input current	V <sub>CC</sub> = MAX; V <sub>IL</sub> = 0.4V			-3 -0.3 -1.6 -0.4	mA	X1 and X2 IVO – IV7 IO – I15 HALT and RESET	
los	Short circuit output current	V <sub>CC</sub> = MAX; (Note: At any time, no more than one output should be connected to ground.)	-30		-140	mA	All output pins	
lcc	Supply current	V <sub>CC</sub> = MAX			175 205	mA	T <sub>C</sub> = 125°C T <sub>A</sub> = -55°C	
IREG	Regulator control	V <sub>CC</sub> = 5.0V	-10		-25	mA	Max available base drive for series-pass transistor	
ICR	Regulator current	V <sub>CC</sub> = MAX			180 260	mA	T <sub>C</sub> = 125°C T <sub>A</sub> = -55°C	

NOTES:

1. Operating temperature ranges are guaranteed after thermal equilibrium has been reached.

2. All voltages measured with respect to ground terminal.

# AC ELECTRICAL CHARACTERISTICS CONDITIONS: $4.5V \le V_{CC} \le 5.5V$ ; $-55^{\circ}C \le T_C \le 125^{\circ}C$ LOADING: (See test circuits)

SYMBOL	PARAMETER (NOTE 1)	LIMITS (INSTRUCTION CYCLE TIME = 200ns)			LIMITS (INSTRUCTION CYCLE TIME > 200ns)			UN-	COMMENTS	
		Min	Тур	Max	Min	Тур	Max	118		
TPC	Processor cycle time	200			200			ns		
T <sub>CP</sub>	X1 clock period	100			100			ns	3	
Т <sub>СН</sub>	X1 clock high time	50			50			ns		
T <sub>CL</sub>	X1 clock low time	50			50			ns		
T <sub>MCL</sub>	MCLK low delay	15		40	15		40	ns		
Τw	MCLK pulse width	30		60	T <sub>4Q</sub> - 10		T <sub>4Q</sub> + 10	ns	Note 2	
TMODO	Output driver turn on time MCLK falling edge	125		148	T <sub>1Q</sub> + T <sub>2Q</sub> + 25		T <sub>1Q</sub> + T <sub>2Q</sub> + 45	ns	Note 9	
T <sub>DI</sub>	Output driver turn-on time (SC/WC rising edge)	20			20			ns	Note 10	
T <sub>DD</sub>	Input data to output data	75		105	75		105	ns		
T <sub>MHS</sub>	MCLK falling edge to HALT falling edge			30			T <sub>1Q</sub> - 20	ns	Note 2	
т <sub>мнн</sub>	HALT hold time (MCLK falling edge)	65			T <sub>10</sub> + 15			ns	Note 2	
TACC	Program storage access time			60				ns	Note 12	
т <sub>ю</sub>	I/O port output enable time (LR/RB to valide IV data input)			20				ns		
TMAS	MCLK falling edge to address stable			140			T <sub>1Q</sub> + T <sub>2Q</sub> + 40	ns	Notes 2, 3, & 4	
TIA	Instruction to address			140			T <sub>2Q</sub> + 90	ns	Notes 2, 3 & 5	
TIVA	Input data to address			95			85	ns	Notes 3 & 6	
T <sub>MIS</sub>	MCLK falling edge to instruction stable			25			T <sub>1Q</sub> - 20	ns	Notes 2 & 10	
т <sub>мін</sub>	Instruction hold time (MCLK falling edge)	55			T <sub>1Q</sub> + 5			ns	Notes 2 & 8	
т <sub>мwн</sub>	MCLK falling edge to SC/WC rising edge	100		128	T <sub>1Q</sub> + T <sub>2Q</sub> + 5		T <sub>1Q</sub> + T <sub>2Q</sub> + 25	ns	Notes 2 & 11	
TMWL	MCLK falling edge to SC/WC falling edge	0		15	0		15	ns		
T <sub>MIBS</sub>	MCLK falling edge to LB/AB (Input phase)	8		25	8		25	ns		
T <sub>IIBS</sub>	Instruction to LB/RB (Input phase)			25			25	ns		
T <sub>MOBS</sub>	MCLK falling edge to LB/RB (Output phase)	115		145	T <sub>1Q</sub> + T <sub>2Q</sub> + 15		T <sub>1Q</sub> + T <sub>2Q</sub> + 45	ns	Note 2	
TMIDS	MCLK falling edge to input data stable			55			T <sub>1Q</sub> + T <sub>2Q</sub> - 45	ns	Note 2	
T <sub>MIDH</sub>	Input data hold time 115 (MCLK falling edge)				T <sub>1Q</sub> + T <sub>2Q</sub> + 15			ns	Notes 2 & 11	

# **PIN CONFIGURATIONS (Continued)**



### **PIN DESCRIPTION**

FLATPACK	LLCC	DIP		FUNCTION
PIN NO.	PIN NO.	PIN NO.	IDENTIFIER	FUNCTION
1	1, 68	1	VCR	Regulated voltage input from series-pass transistor (2N5320 or equivalent).
2-9, 47-51	4-11, 62-66	2-9, 45-49	A0 - A12	<b>Program Address Lines:</b> These active-high outputs permit direct addressing of up to 8192 words of program storage; $A_{12}$ is least significant bit.
10-11	12, 13	10, 11	X1, X2	Timing generator connections for a capacitor, a series resonant crystal, or an external clock source with complementary outputs.
12	2,3, 14-16	12	GND	Ground.
13-28	17-23, 28-36	13-28	l <sub>0</sub> – l <sub>15</sub>	Instruction Lines: These active-high input lines receive 16-bit instructions from program storage; I15 is least significant bit.
29	37	29	SC	Select Command: When high (binary 1), an address is being output on pins $\overline{IVO}$ through $\overline{IV7}$ .
31	38	30	wc	Write Command: When high (binary 1), data is being output on pins $\overline{IV0}$ through $\overline{IV7}$ .

### **PIN DESCRIPTION (Continued)**

FLATPACK	LLCC	DIP			
PIN NO.	PIN NO.	PIN NO.	IDENTIFIER	FUNCTION	
31	39	31	Left Bank Control: When low (binary 0), devices connected to the Left Ba accessed. (Note. Typically, the LB signal is tied to the ME input pin peripherals).		
32	45	32	RB	RB <b>Right Bank Control:</b> When low (binary 0), devices connected to the Right Ban are accessed (Note. Typically, the RB signal is tied to the ME input pin of 1/4 peripherals).	
35-38, 40-43	46-49, 55-58	33-36, 38-41	170 - 177	Interface Vector (Input/Output Bus) — these bidirectional active-low three-state lines communicate data and/or addresses to I/O devices and memory locations. A low voltage level equals a binary "1"; IV7 is Least Significant Bit.	
39	50-52	37	Vcc	+5V power supply.	
44	59	42	MCLK	Master Clock: This active-high output signal is used for clocking I/O devices and/ or synchronization of external logic.	
45	60	43	RESET	When <b>RESET</b> input is low (binary 0), the 8X305 is initialized — sets Program Counter/Address Register to zero and inhibits MCLK. For the period of time RESET is low, the Left Bank/Right Bank (LB/RB) signals are forced high asynchronously.	
46	61	44	HALT	When <b>HALT</b> input is low (binary 0), internal operation of the 8X305 stops at the start of next instruction; MCLK is not inhibited nor is any internal register affected; however, both the Left Bank/Right Bank (LB/RB) signals are synchronously driven high during the first quarter of the instruction cycle time and remain high during the time HALT is low.	
52	67	50	VR	Internally-generated reference output voltage for external series-pass regulator transistor.	
33, 34	24-27, 40-44, 53, 54		No Connect		



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